

1. General description

Planar passivated high commutation three quadrant triac in a TO252(DPAK) surface mountable plastic package. This "series ET" triac balances the requirements of commutation performance and gate sensitivity and is intended for interfacing with low power drivers and logic ICs including microcontrollers.

2. Features and benefits

- 3Q technology for improved noise immunity
- Direct interfacing with low power drivers and microcontrollers
- Good immunity to false turn-on by dV/dt
- High commutation capability with sensitive gate
- High voltage capability
- Planar technology for voltage ruggedness and reliability
- Sensitive gate for easy logic level triggering
- Triggering in three quadrants only
- Surface mountable package

3. Applications

- General purpose motor controls
- Small appliances (White Goods)
- Loads such as contactors, circuit breakers, valves, dispensers and door locks
- Lower-power highly inductive, resistive and safety loads

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V _{DRM}	repetitive peak off-state voltage			800			V
I _{T(RMS)}	RMS on-state current	full sine wave; T _{mb} ≤ 135 °C; Fig. 1 ; Fig. 2 ; Fig. 3		4			A
I _{TSM}	non-repetitive peak on-state current	full sine wave; T _{j(init)} = 25 °C; t _p = 20 ms; Fig. 4 ; Fig. 5		35			A
		full sine wave; T _{j(init)} = 25 °C; t _p = 16.7 ms		38.5			A
T _j	operating junction temperature			-40 to 150			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _j = 25 °C; Fig. 7		-	-	10	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _j = 25 °C; Fig. 7		-	-	10	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _j = 25 °C; Fig. 7		-	-	10	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; Fig. 9		-	-	20	mA
V _T	on-state voltage	I _T = 4.0 A; T _j = 25 °C; Fig. 10		-	-	1.5	V

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}$; $T_j = 125 \text{ }^\circ\text{C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit		600	-	-	V/ μs
dI_{com}/dt	rate of change of commutating current	$V_D = 400 \text{ V}$; $T_j = 150 \text{ }^\circ\text{C}$; $I_{T(RMS)} = 2 \text{ A}$; $dV_{com}/dt = 20 \text{ V}/\mu\text{s}$; (snubberless condition); gate open circuit		3	-	-	A/ms

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BTA304S-800ET	TO252	BTA304S-800ETJ	Reel	2500	TO252N	04-Nov-2016
					TO252Q	05-Mar-2025

7. Marking

Table 4. Marking codes

Type number	Marking codes	
	Assembly factory: N	Assembly factory: Q
BTA304S-800ET	BT304S 800ET PJNxxxx xx	BT304S 800ET PJQxxxx xx

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Max	Unit
V_{DSM}	non-repetitive peak off-state voltage			900	V
V_{RSM}	non-repetitive peak reverse voltage			900	V
V_{DRM}	repetitive peak off-state voltage			800	V
V_{RRM}	repetitive peak reverse voltage			800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 135\text{ }^{\circ}\text{C}$; Fig 1 ; Fig 2 ; Fig 3		4	A
I_{TSM}	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_p = 20\text{ ms}$; Fig 4 ; Fig 5		35	A
		full sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_p = 16.7\text{ ms}$		38.5	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN		6.1	A^2s
dI_T/dt	rate of rise of on-state current	$I_G = 20\text{ mA}$		100	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current			2	A
P_{GM}	peak gate power			5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		0.5	W
T_{stg}	storage temperature			-40 to 150	$^{\circ}\text{C}$
T_j	operating junction temperature			-40 to 150	$^{\circ}\text{C}$

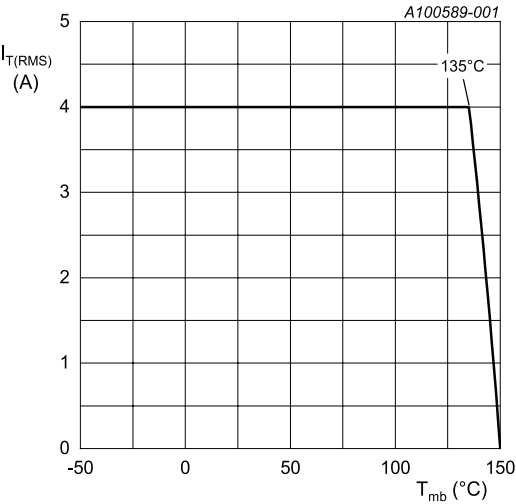


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

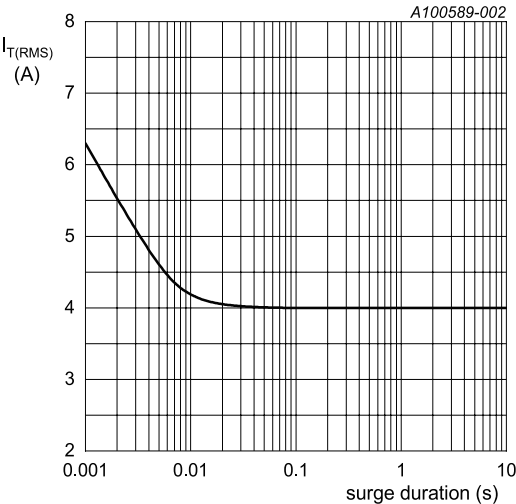


Fig. 2. RMS on-state current as a function of surge duration; maximum values

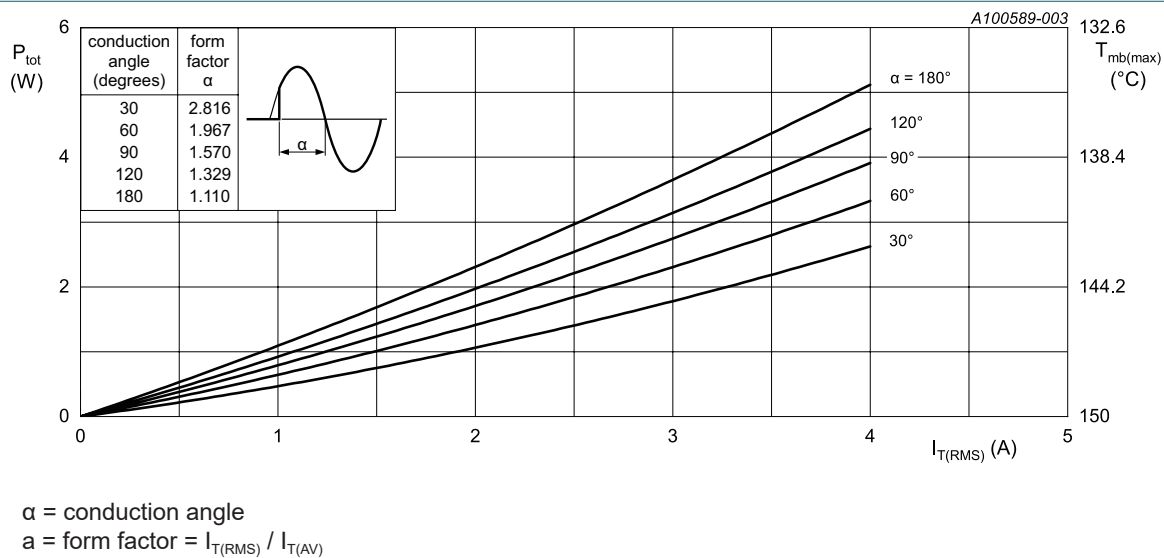


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

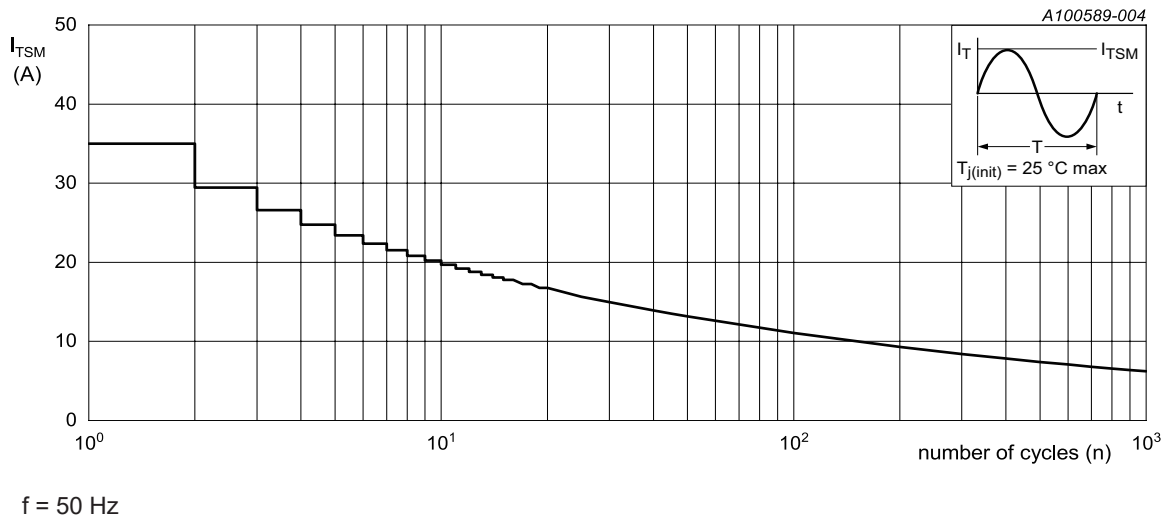


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

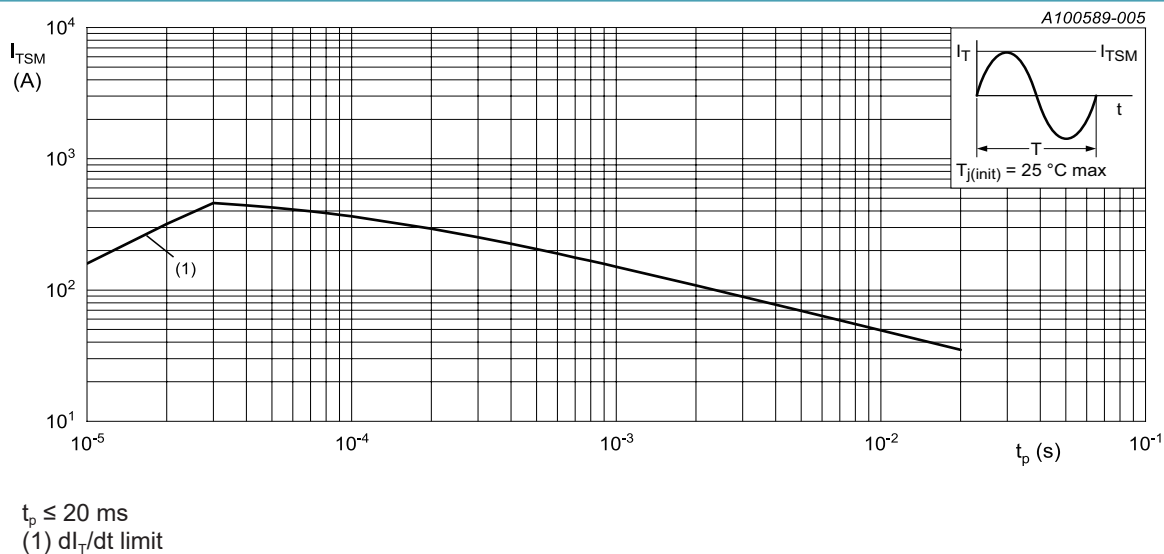
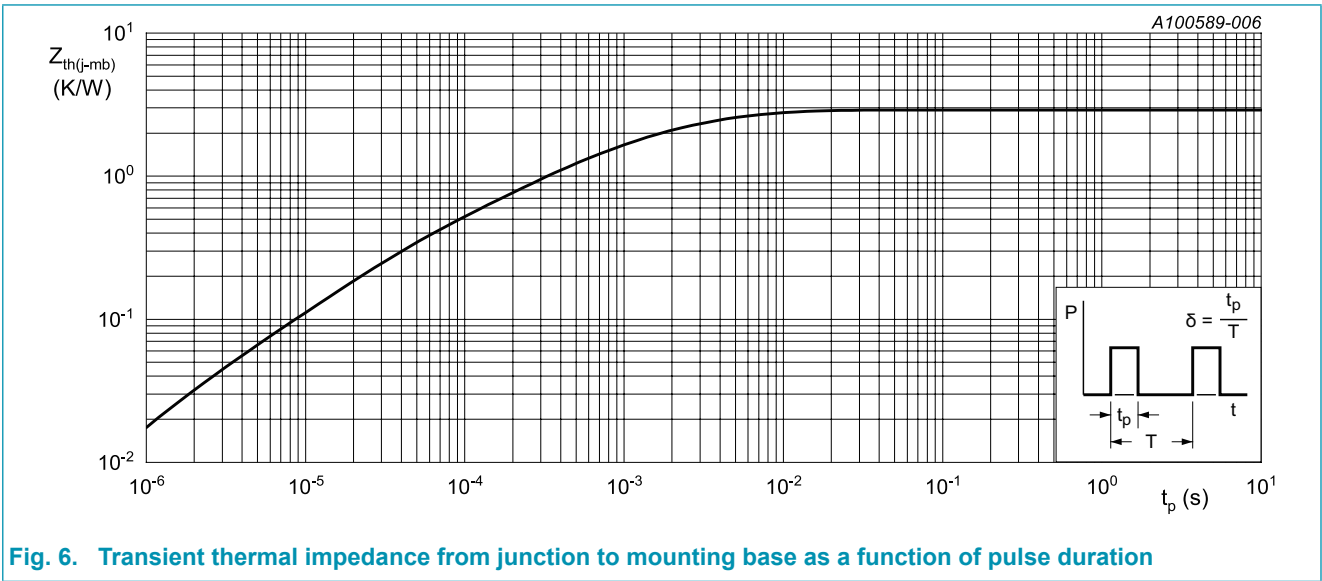


Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6	-	-	2.9	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air; printed circuit board (FR4) mounted	-	50	-	K/W



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T2+ G+; T _J = 25 °C; Fig. 7		-	-	10	mA
		V _D = 12 V; I _T = 0.1 A; T2+ G-; T _J = 25 °C; Fig. 7		-	-	10	mA
		V _D = 12 V; I _T = 0.1 A; T2- G-; T _J = 25 °C; Fig. 7		-	-	10	mA
I _L	latching current	V _D = 12 V; I _G = 0.1 A; T2+ G+; T _J = 25 °C; Fig. 8		-	-	30	mA
		V _D = 12 V; I _G = 0.1 A; T2+ G-; T _J = 25 °C; Fig. 8		-	-	40	mA
		V _D = 12 V; I _G = 0.1 A; T2- G-; T _J = 25 °C; Fig. 8		-	-	30	mA
I _H	holding current	V _D = 12 V; T _J = 25 °C; Fig. 9		-	-	20	mA
V _T	on-state voltage	I _T = 4.0 A; T _J = 25 °C; Fig. 10		-	-	1.5	V
V _{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A; T _J = 25 °C; Fig. 11		-	-	1	V
		V _D = 400 V; I _T = 0.1 A; T _J = 150 °C		0.2	-	-	V
I _D	off-state current	V _D = 800 V; T _J = 25 °C		-	-	10	μA
		V _D = 800 V; T _J = 150 °C		-	-	2	mA
I _R	reverse current	V _R = 800 V; T _J = 25 °C		-	-	10	μA
		V _R = 800 V; T _J = 150 °C		-	-	2	mA
Dynamic characteristics							
dV _D /dt	rate of rise of off-state voltage	V _{DM} = 536 V; T _J = 125 °C; (V _{DM} = 67% of V _{DRM}); exponential waveform; gate open circuit		600	-	-	V/μs
dI _{com} /dt	rate of change of commutating current	V _D = 400 V; T _J = 150 °C; I _{T(RMS)} = 2 A; dV _{com} /dt = 20 V/μs; (snubberless condition); gate open circuit		3	-	-	A/ms

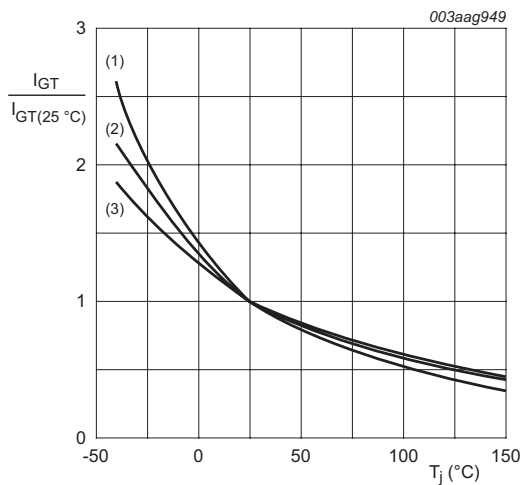


Fig. 7. Normalized gate trigger current as a function of junction temperature

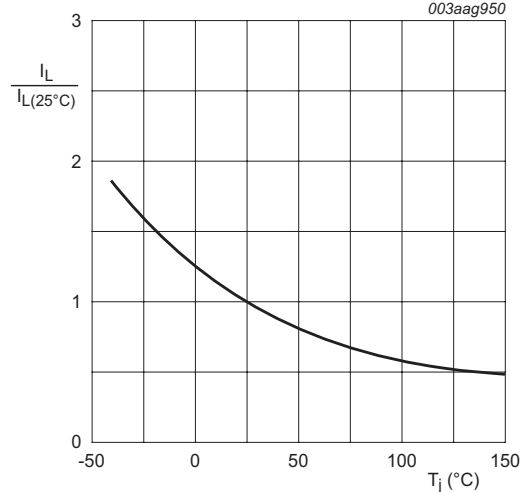


Fig. 8. Normalized latching current as a function of junction temperature

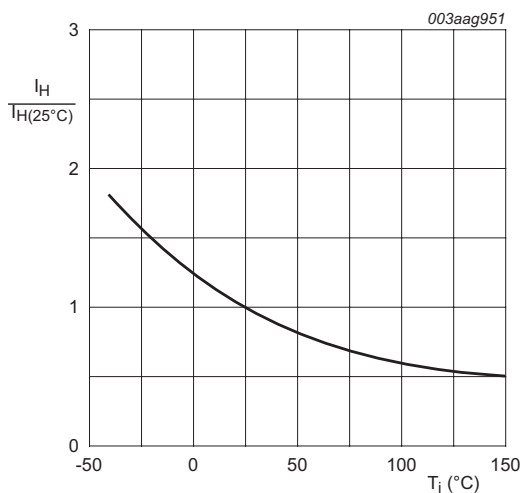
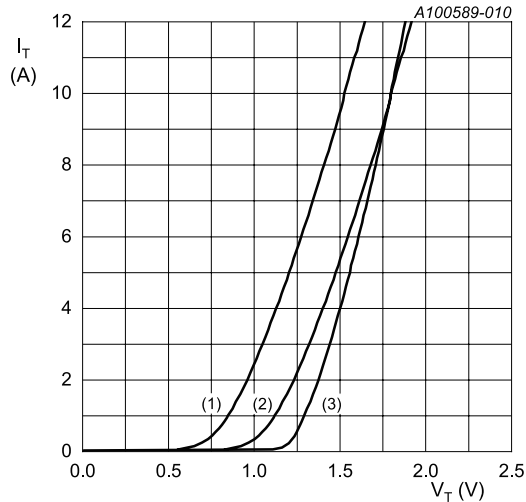


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.143 \text{ V}; R_s = 0.0625 \Omega$
(1) $T_j = 150^{\circ}\text{C}$; typical values
(2) $T_j = 150^{\circ}\text{C}$; maximum values
(3) $T_j = 25^{\circ}\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

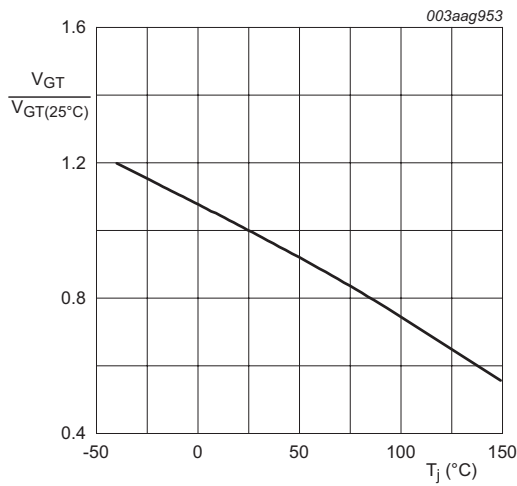
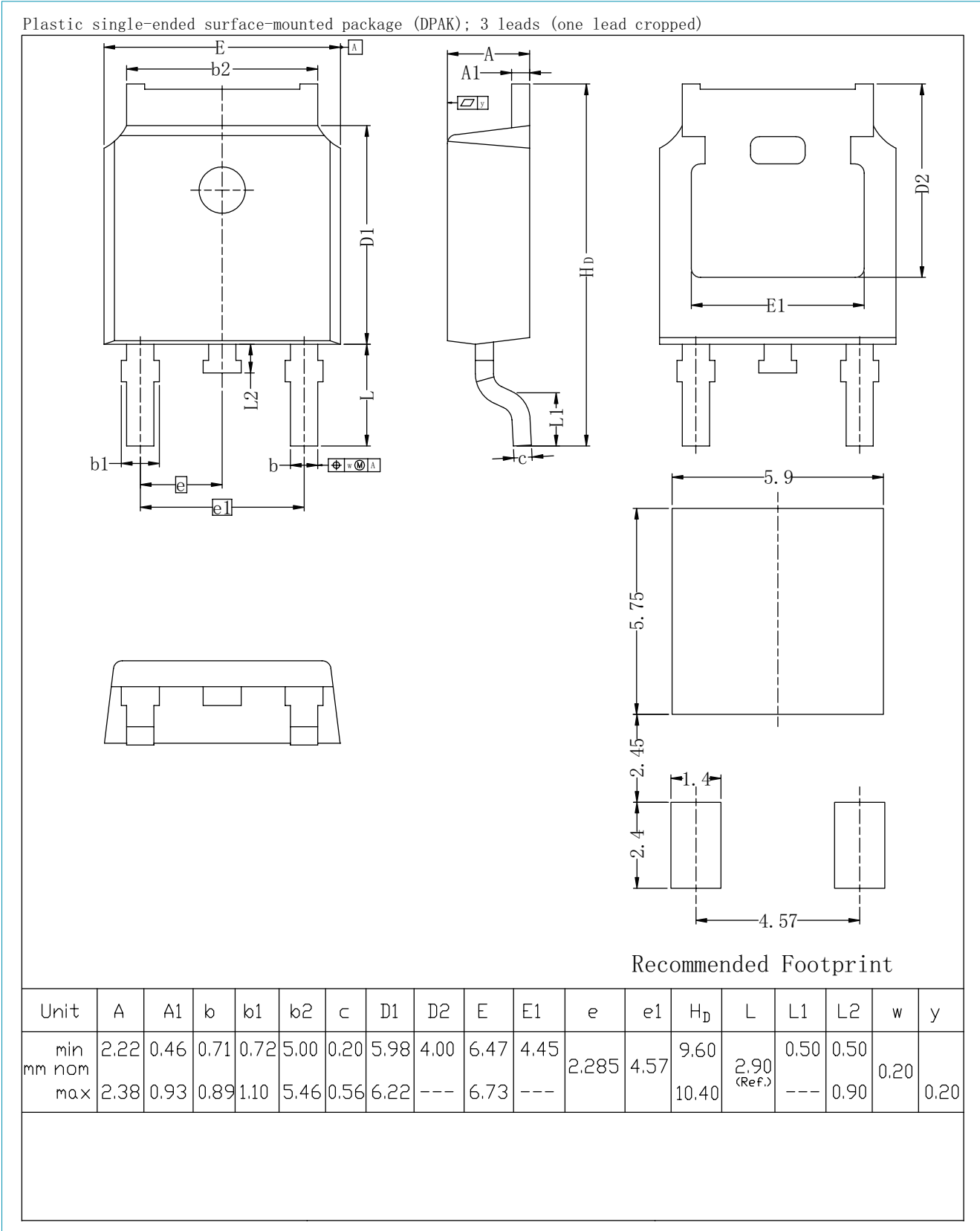


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

11. Package outline

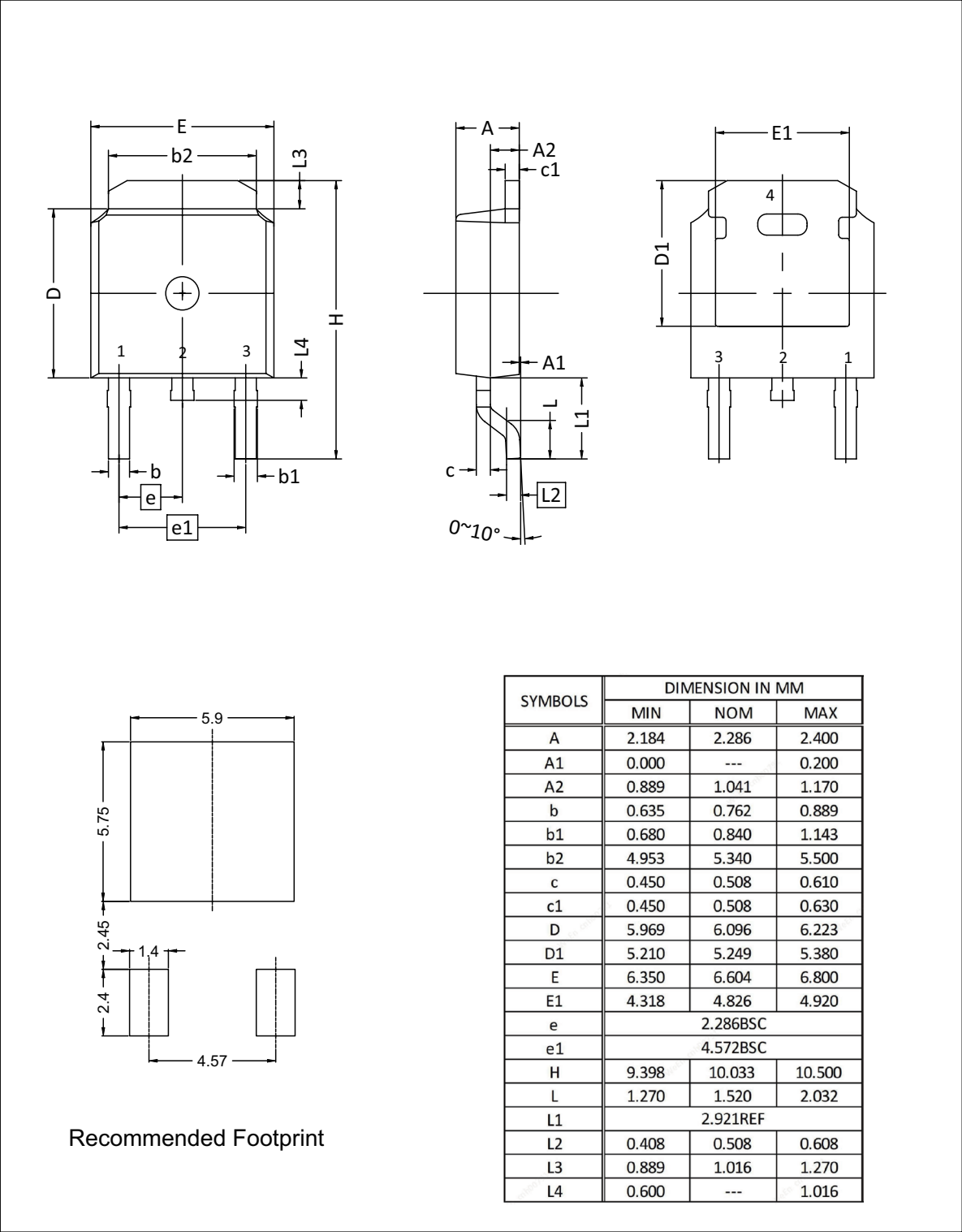
Assembly factory: N



Assembly factory: Q

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)

TO252



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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